AN 1980-21388C [12] WPIDS
TI **Soldering** material for external parts of watch - comprises gold-**tin alloy** of low **soldering** temperature and high corrosion resistance.
DC M23 M26 S04
PA (SUWA) SUWA SEIKOSHA KK
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PI JP 55020403 A 19800213 (198012)*
PRAI JP 1978-88713 19780720
AB JP 55020403 A UPAB: 19930902
A **soldering** material consists of Au 10-85 weight% and Sn 15-90 weight% and >=1 of **Ni** 0.1-1 weight%, **Cu** 0.1-15 weight%, **Ag** 3-48 weight%, P 0.2-15 weight%, **Co** 0.1-2 weight%, Ca 0.1-3 weight%, Mn 0.1-3 weight%, Pt 0.1-5 weight%, Sb 0.1-64 weight%, Se 0.05-0.5 weight% and Te 0.05-2 weight%.

The Au-**Sn base alloy** has high corrosion resistance and low **soldering** temperature, nonsequently softening of the external parts can be prevented and also strain relief annealing can be achieved in **soldering** with the **soldering** material. The melting point of the Au-**Sn alloy** of <85% of Au is <=500 degrees C, especially the eutectic alloy of Au 80% and Sn 20% has a melting point of 280 degrees C, at which brass, **nickel**, **silver** and stainless steel do not soften.